

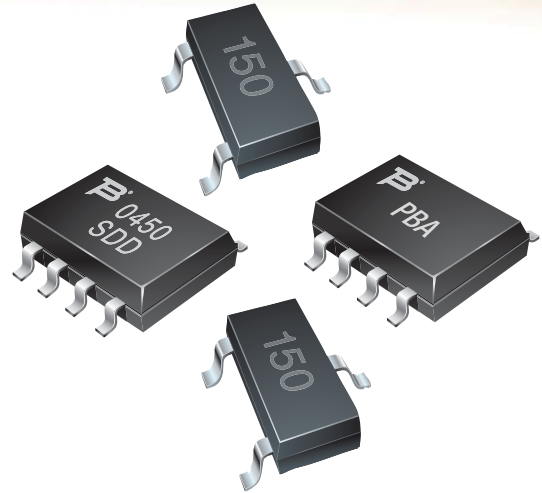


Product Change Notification

CHIP DIODES

Bourns Manufacturers Representatives
Corporate Distributor Product Managers
Americas Sales Team
Asia Sales Team
Europe Sales Team

April, 2010



Bourns® Diode Products Addition of Second Wafer Fabrication Location and Change to “Green” Compliance

Bourns is adding a second wafer fabrication location, in the UK, for the diode part numbers listed below for continued secure supply chain management and delivery support to our customers.

Bourns P/N
CDSOT23-SM712
CDNBS08-PLC03-6
CDNBS08-SLVU2.8-8
CDSOT23-SLVU2.8

Bourns will change to the Green Sumitomo G600 mold compound in the above packages pursuant to our plan to offer “Green” products to our customers in 2010. Some products will be available in the new “Green” mold compound immediately if requested by customers.

Reliability data, SGS and MDS reports on the units’ package assembly incorporating the above changes will be available on or before June 30, 2010.

Bourns is issuing 90 days notice that mass production using the above changes will be available beginning August 1, 2010.